



PK736 (v1.0) May 29, 2015

100% Material Declaration Data Sheet Spartan®-6 Cu Wire FG900 Package

Average Weight: 4.2148 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.090946	2.158%
	Silicon	7440-21-3	100.00	Main material	0.090946	
Die Attach Material					0.016016	0.380%
	Silver	7440-22-4	77.50	Main material	0.012412	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.002402	
	Acrylate monomer	Trade Secret	7.50	Main material	0.001201	
Copper Wire					0.008441	0.200%
	Cu	7440-50-8	98.25	Main material	0.008293	
	Pd	7440-05-3	1.75	Dopant	0.000148	
Mold Compound					1.878392	44.567%
	Epoxy Resin	Trade secret	3.00	Main material	0.056352	
	Phenol Resin A	9003-35-4	3.00	Main material	0.056352	
	Phenol Resin B	Trade secret	3.00	Main material	0.056352	
	Silica(Amorphous) A	60676-86-0	72.45	Filler	1.360895	
	Silica(Amorphous) B	7631-86-9	15.00	Filler	0.281759	
	Metal Hydroxide	Trade secret	3.00	Flame retardant	0.056352	
	Carbon black	1333-86-4	0.55	Color agent	0.010331	
Solder Balls					0.856617	20.324%
	Tin (Sn)	7440-31-5	63.00	Main material	0.539669	
	Lead (Pb)	7439-92-1	37.00	Main material	0.316948	

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Substrate					1.364376	32.371%
	Au	7440-57-5	1.18	Main material	0.016077	
	Ni	7440-02-0	8.36	Main material	0.114059	
	Cu foil	7440-50-8	2.56	Main material	0.034922	
	Cu plating	7440-50-8	18.45	Plating	0.251726	
	Continuous Filament Fiber Glass	65997-17-3	19.06	Glass Fiber	0.260040	
	BT Core	7440-50-8 N/A	34.76	Core	0.474263	
	Solder Mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 91-20-3 85954-11-6 N/A	11.21	Solder mask	0.152928	
	Prepregs	NA	4.42	Prepregs	0.060362	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/29/15	1.0	Initial Xilinx release

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